

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

: MAIL STOP: RCE

Akihisa HONGO et al.

Docket No. 2001 0133A

Serial No. 09/762,582

Group Art Unit 1753

Filed April 12, 2001

Examiner Brian Mutschler

SUBSTRATE PLATING METHOD AND APPARATUS Confirmation No. 5731

PRELIMINARY AMENDMENT

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450 THE COMMISSIONER IS AUTH TO CHARGE ANY DEFICIENCY OF FEES FOR THIS PAPER TO DEPO ACCOUNT NO. 23-0975

Sir:

In response to the Office Action of October 27, 2004, the period for response to which having been extended by three months to April 27, 2005, please amend the above-identified U.S. Patent application as follows: